



**REVERSE VOLTAGE: 50 - 1000 V**  
**FORWARD CURRENT: 1.0 A**

## Features

Plastic package has Underwriters Laboratory Flammability Classification 94V-O

- For surface mounted applications
- High temperature metallurgically bonded construction
- Fast switching for high efficiency

- ◇ Cavity-free glass passivated junction
- ◇ Capable of meeting environmental standards of MIL-S-19500
- ◇ High temperature soldering : 250°C /10 seconds at terminals

## Mechanical Data

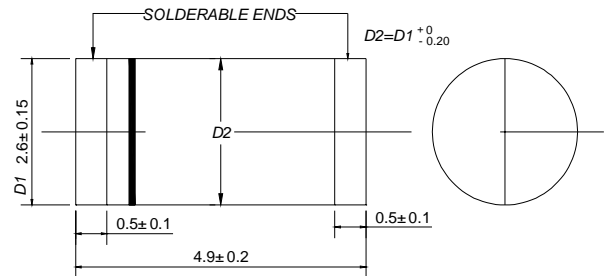
Case: JEDEC DO-213AB, molded plastic over passivated chip

Polarity: Color band denotes cathode end

Weight: 0.0046 ounces, 0.116 gram

Mounting position: Any

## DO - 213AB



Dimensions in millimeters

## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

		HSM 101	HSM 102	HSM 103	HSM 104	HSM 105	HSM 106	HSM 107	HSM 108	UNITS
Maximum recurrent peak reverse voltage	$V_{RRM}$	50	100	200	300	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	210	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	300	400	600	800	1000	V
Maximum average forward rectified current $T_A=50$	$I_{(AV)}$	1.0								A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	$I_{FSM}$	30								A
Maximum forward voltage at 1.0A	$V_F$	1.0		1.3		1.7				V
Maximum DC reverse current @ $T_j=25$ at rated DC blocking voltage @ $T_j=100$	$I_R$	5.0				100				$\mu A$
Maximum reverse recovery time (Note1)	$t_{rr}$	50				75				ns
Typical thermal resistance (NOTE 2)	$R_{\theta JT}$	30								K/W
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$	60								K/W
Operating temperature range	$T_j$	- 55 --- + 175								
Storage temperature range	$T_{STG}$	- 55 --- + 175								

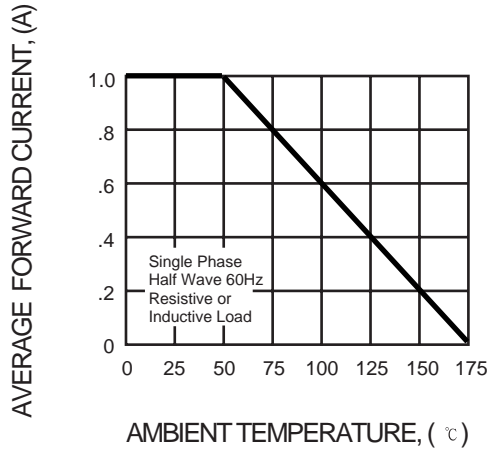
NOTES:1. Measured with  $I_F=0.5A$ ,  $I_R=1A$ ,  $I_{rr}=0.25A$ .

2. Thermal resistance junction to terminal, 6.0 mm<sup>2</sup> copper pads to each terminal.

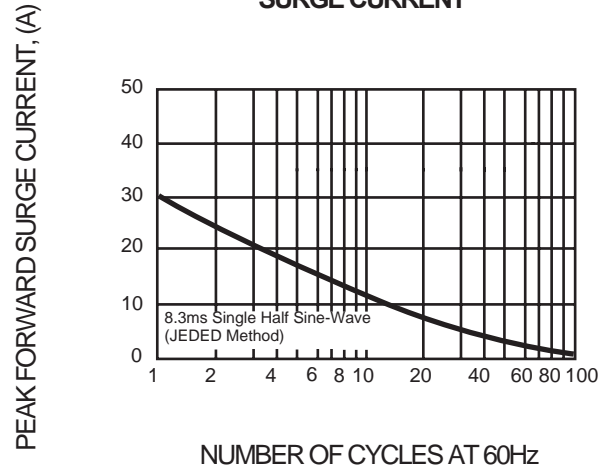
3. Thermal resistance junction to ambient, 6.0 mm<sup>2</sup> copper pads to each terminal.

## Ratings AND Characteristic Curves

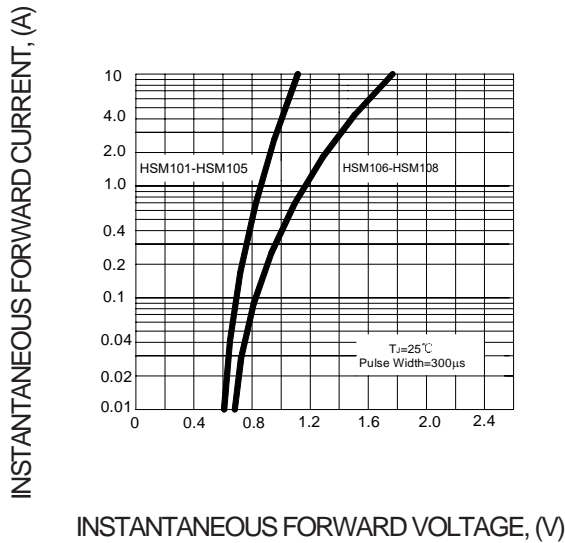
**FIG. 1 - TYPICAL FORWARD CURRENT DERATING CURVE**



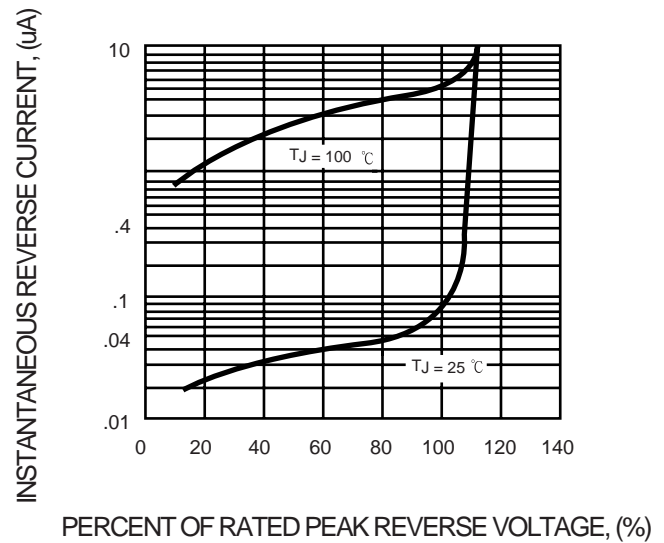
**FIG. 2 - MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT**



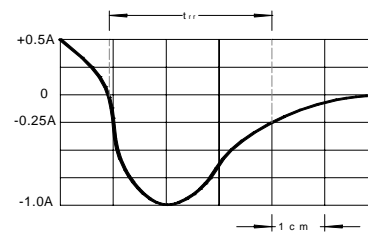
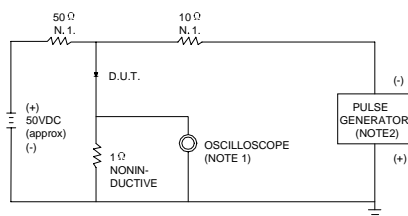
**FIG. 3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS**



**FIG. 4 - TYPICAL REVERSE CHARACTERISTICS**



**FIG.5 – TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC**



NOTES:1.RISE TIME = 7ns MAX.INPUT IMPEDANCE = 1M Ω 22pF. SET TIME BASE FOR 25 ns/cm  
2.RISE TIME =10ns MAX.SOURCE IMPEDANCE=50 Ω

PACKAGE	SPQ/PCS	CARTON SPQ/PCS	CARTON SIZE/CM	CARTON GW/KG	CARTON NW/KG
DO-213AB	5000/REEL	80000	36.0X35.8X36.5	18.00	16.00